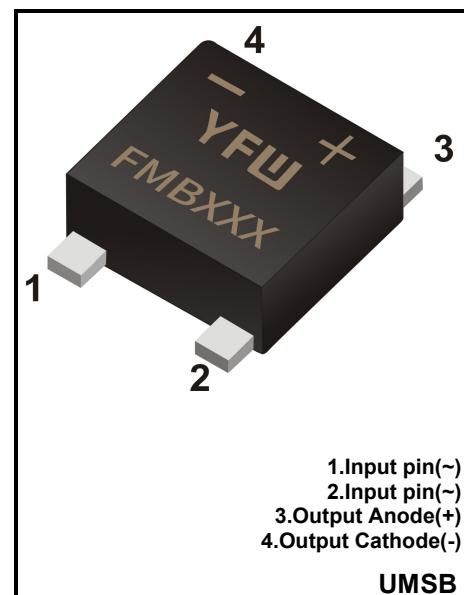


**3.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE**
**RECTIFIER Reverse Voltage - 100 to 1000 V**
**Forward Current – 3.0A**
**FEATURES**

- ◆ Fast reverse recovery time
- ◆ Designed for Surface Mount Application
- ◆ Glass Passivated Chip Junction
- ◆ Low power loss, high efficiency
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives


**MECHANICAL DATA**

- ◆ Case: UMSB
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.234g / 0.00824oz


**Maximum Ratings and Electrical characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified.

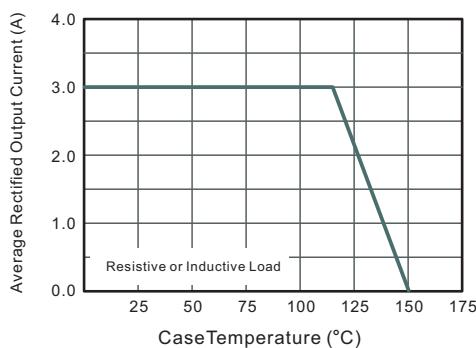
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMSB30B	FMSB30D	FMSB30G	FMSB30J	FMSB30K	FMSB30M	Units			
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V			
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V			
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V			
Average Rectified Output Current at $T_c = 115^\circ C$	$I_o$	3.0						A			
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	$I_{FSM}$	90						A			
Forward Voltage per element at 3.0A	$V_F$	1.1						V			
Maximum DC Reverse Current @ $T_A=25^\circ C$ at Rated DC Blocking Voltage @ $T_A=125^\circ C$	$I_R$	5.0 200						$\mu A$			
Typical Junction Capacitance <sup>(Note1)</sup>	$C_j$	40						pF			
Maximum Reverse Recovery Time <sup>(Note2)</sup>	$T_{rr}$	150		250	500			nS			
Typical Thermal Resistance <sup>(Note3)</sup>	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	65 15 30						$^\circ C/W$			
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^\circ C$			

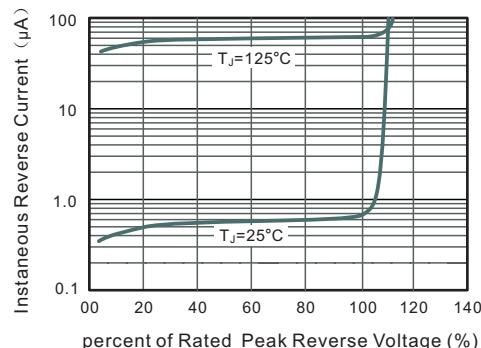
(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

 (2) Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm<sup>2</sup>) copper pad.

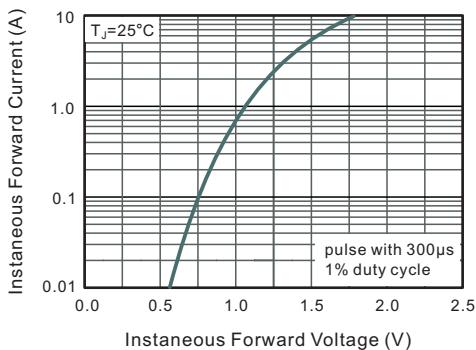
**Fig.1 Average Rectified Output Current Derating Curve**



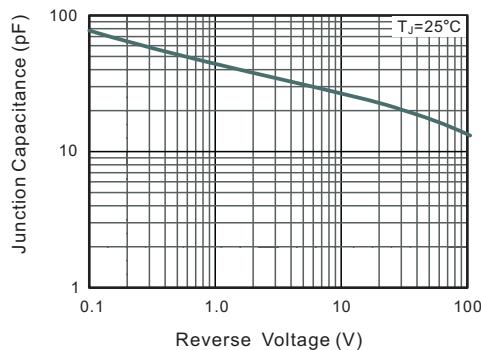
**Fig.2 Typical Reverse Characteristics**



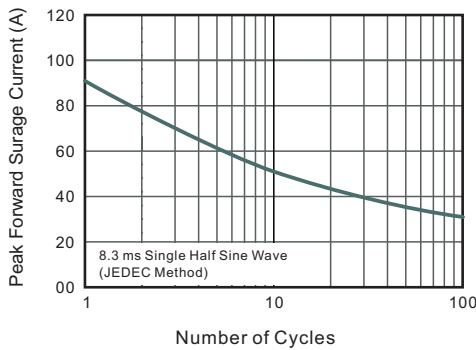
**Fig.3 Typical Instantaneous Forward Characteristics**



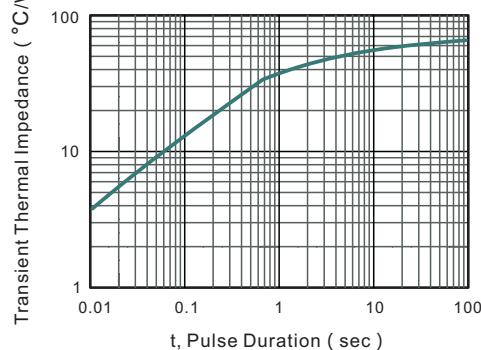
**Fig.4 Typical Junction Capacitance**



**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



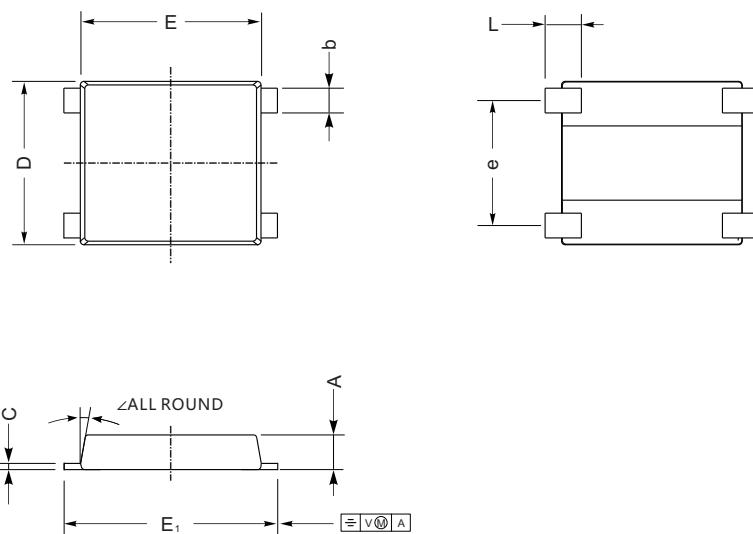
**Fig.6- Typical Transient Thermal Impedance**



### Package Outline

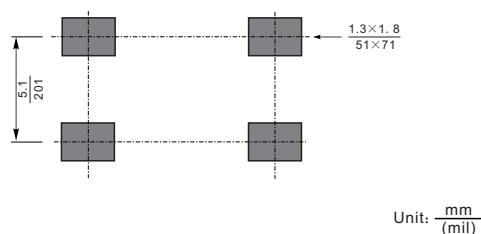
UMSB

Plastic surface mounted package; 4leads



UNIT		A	C	D	E	E <sub>1</sub>	L	e	b	∠
mm	max	1.5	0.29	7.0	7.6	8.9	1.6	5.3	1.15	10°
	min	1.3	0.17	6.2	7.1	8.4	1.0	4.9	0.95	
mil	max	59	12	276	299	350	55	209	45	10°
	min	51	7	244	280	331	31.5	193	37	

### The recommended mounting pad size



### Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
UMSB	Tape/Reel,13"reel	3000	EIA-481-1